Patents (PATENT)

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                 <author role="aut"><!-- %%mandatory field -->

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                       <forename type="first">Thomas</forename>

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                       <forename type="first">Thomas</forename>

                       <surname>Boatwright</surname>

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                 <abstract xml:lang="en">A manufacturing process is applicable to singulating die from a substrate, where the substrate has a layer distinguishable from the substrate by a mechanical property such as brittleness. The process can include providing a workpiece including a substrate and a layer disposed on a first surface, modifying the mechanical property such as by compression, deforming a region of the substrate proximate to the portion of the layer having the modified mechanical property; and fracturing the portion of the layer at a location proximate to the deformed region of the substrate. Also, the process can include propagating a crack through a region of the substrate on a line along the modified portion of the layer. A die formed in this manner is also provided.</abstract>

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